Absolute Maximum Ratings



MiniSKiiP® 0

SKiiP 03NAC12T4V1

Features*

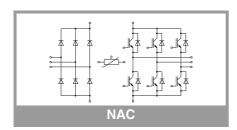
- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

Remarks

- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{j,op}=-40...+150°C)
- Temperature sensor: No basic insulation to main circuit, max. potential difference 850V to -DC

Symbol	Conditions		Values	Unit			
Inverter - IGBT							
V _{CES}	T _j = 25 °C		1200	V			
Ic	T _i = 150 °C	T _s = 25 °C	7.5	Α			
	1 _j = 150 C	T _s = 70 °C	7.5	Α			
I _C	T _i = 175 °C	T _s = 25 °C	7.5	Α			
	1 _j = 1/5 °C	T _s = 70 °C	7.5	Α			
I _{Cnom}			8	Α			
I _{CRM}			24	Α			
V_{GES}			-20 20	V			
t _{psc}	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 1200 \text{ V}$	T _j = 150 °C	10	μs			
Tj			-40 175	°C			
Inverse - I	Diode			•			
V_{RRM}	T _j = 25 °C		1200	V			
IF	T 150°C	T _s = 25 °C	9	Α			
	T _j = 150 °C	T _s = 70 °C	9	Α			
IF	T _j = 175 °C	T _s = 25 °C	9	Α			
		T _s = 70 °C	9	Α			
I _{FRM}			24	Α			
I _{FSM}	$t_p = 10 \text{ ms, sin } 180^\circ, T_j = 150 ^\circ\text{C}$		36	Α			
Tj			-40 175	°C			
Rectifier -	Diode						
V_{RRM}	T _j = 25 °C		1600	V			
IF	$T_s = 25 ^{\circ}\text{C}, T_j = 150$		39	Α			
I _{FSM}	$t_p = 10 \text{ ms}$	T _j = 25 °C	220	Α			
	sin 180°	T _j = 150 °C	200	Α			
i ² t	$t_p = 10 \text{ ms}$	T _j = 25 °C	242	A ² s			
sin 180°		T _j = 150 °C	200	A ² s			
T _j			-40 150	°C			
Module							
I _{t(RMS)}	$T_{terminal} = 80 ^{\circ}C, 20$	A per spring	t.b.d.	Α			
T _{stg}	module without TIM	1	-40 125	°C			
V _{isol}	AC sinus 50 Hz, 1 r	min	2500	V			

Characteristics								
Symbol	Conditions	min.	typ.	max.	Unit			
Inverter -	Inverter - IGBT							
$V_{CE(sat)}$ $I_C = 8 A$	_	T _j = 25 °C		1.85	2.10	V		
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.25	2.45	V		
V_{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V		
	Chipievei	T _j = 150 °C		0.70	0.80	V		
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		131	150	mΩ		
	chiplevel	T _j = 150 °C		194	206	mΩ		
$V_{GE(th)}$	$V_{GE} = V_{CE} V$, $I_C = 1 \text{ mA}$		5	5.8	6.5	V		
I _{CES}	$V_{GE} = 0 V$	T _j = 25 °C			1	mA		
	V _{CE} = 1200 V			-		mA		
C _{ies}	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	f = 1 MHz		0.49		nF		
Coes		f = 1 MHz		0.05		nF		
C _{res}		f = 1 MHz		0.03		nF		





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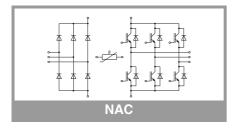
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- Temperature sensor: No basic insulation to main circuit, max. potential difference 850V to -DC

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Inverter - IGBT								
Q_{G}	V _{GE} = - 8 V+ 15	V		45		nC		
R _{Gint}	T _j = 25 °C			0		Ω		
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		32		ns		
t _r	I _C = 8 A	T _j = 150 °C		34		ns		
E _{on}	$R_{G \text{ on}} = 47 \Omega$ $R_{G \text{ off}} = 47 \Omega$	T _j = 150 °C		0.9		mJ		
t _{d(off)}	□G off — 47 32	T _j = 150 °C		ns				
t _f		T _j = 150 °C		68		ns		
E _{off}	$V_{GE} = +15/-15 \text{ V}$	T _j = 150 °C		0.7		mJ		
R _{th(j-s)}	per IGBT, λ _{paste} =0	.8 W/(K*m)		1.84		K/W		
Inverse -	Diode							
$V_F = V_{EC}$	I _F = 8 A	T _j = 25 °C		2.33	2.65	V		
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.35	2.68	V		
V_{F0}	chiplevel	T _j = 25 °C		1.30	1.50	V		
	Criipievei	T _j = 150 °C		0.90	1.10	V		
r _F	chiplevel	T _j = 25 °C		129	144	$m\Omega$		
	Chipicvei	T _j = 150 °C		181	198	$m\Omega$		
I _{RRM}	$I_F = 8 A$	T _j = 150 °C		7.7		Α		
Q _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 150 °C		1.23		μC		
E _{rr}	$di/dt_{off} = 335 \text{ A/}\mu\text{s}$	T _j = 150 °C		0.5		mJ		
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(K*m)		2.53			K/W		
Rectifier -	- Diode							
$V_F = V_{EC}$	I _F = 8 A	T _j = 25 °C		1.00	1.21	V		
	I _F = 8 A	T _j = 125 °C		0.90	1.10	V		
V_{F0}	chiplevel	T _j = 25 °C		0.88	0.98	V		
	Criipievei	T _j = 125 °C		0.73	0.83	V		
r _F	chiplevel	T _j = 25 °C		15	29	mΩ		
	omplever	T _j = 125 °C		21	34	mΩ		
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0$	0.8 W/(K*m)		1.5		K/W		
Module								
Ms	to heat sink		2		2.5	Nm		
w				20		g		
Temperat	Temperature Sensor							
R ₁₀₀	T _r = 100 °C, tolera		1670 ± 3%		Ω			
R _(T)	$R_{(T)}=1000\Omega[1+A(T)]$, $A = 7.635*10^{-3}$ °C $B = 1.731*10^{-5}$ °C							



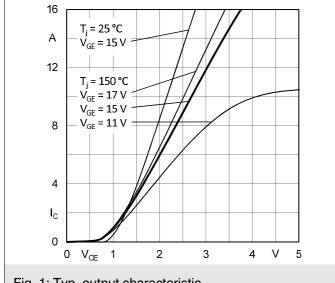


Fig. 1: Typ. output characteristic

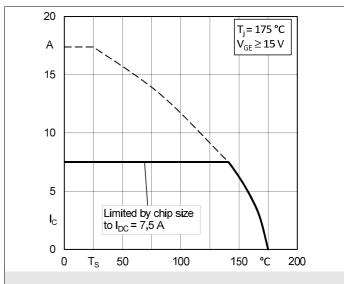


Fig. 2: Typ. rated current vs. temperature $I_C = f(T_S)$

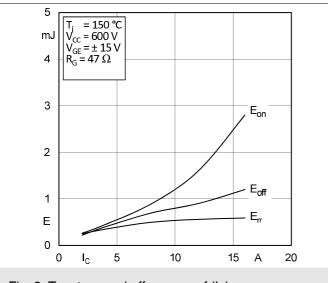


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

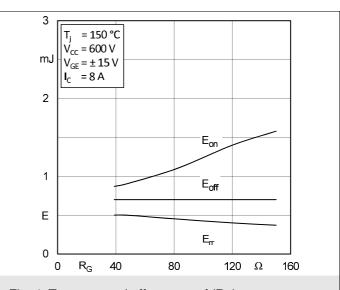


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

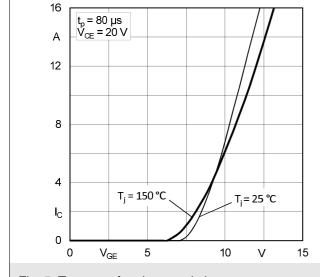


Fig. 5: Typ. transfer characteristic

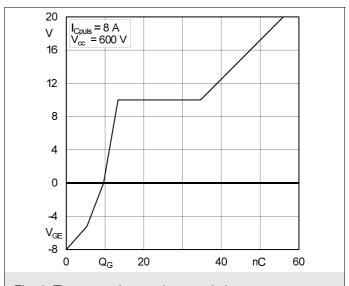
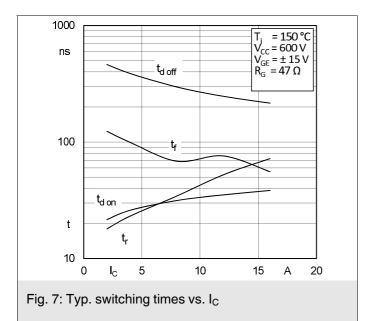
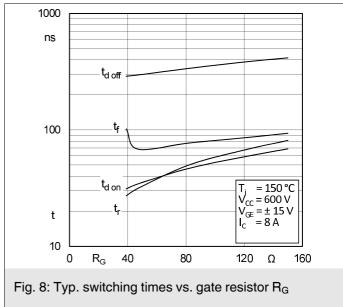
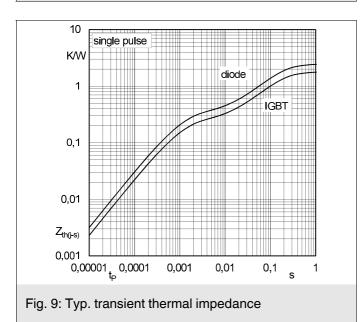
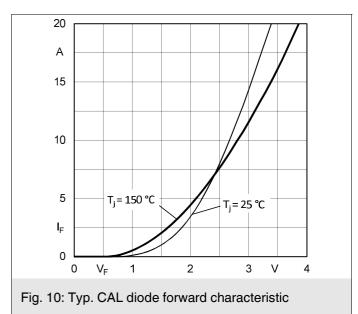


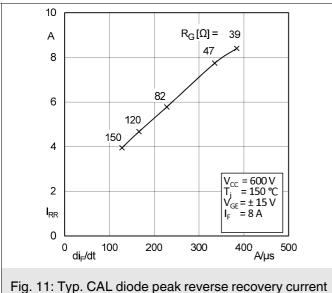
Fig. 6: Typ. gate charge characteristic

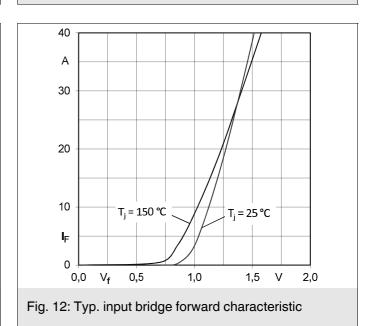






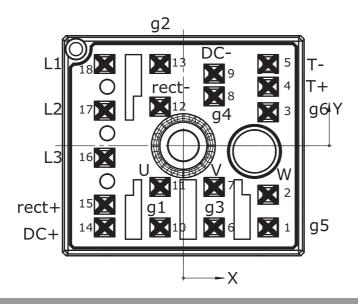




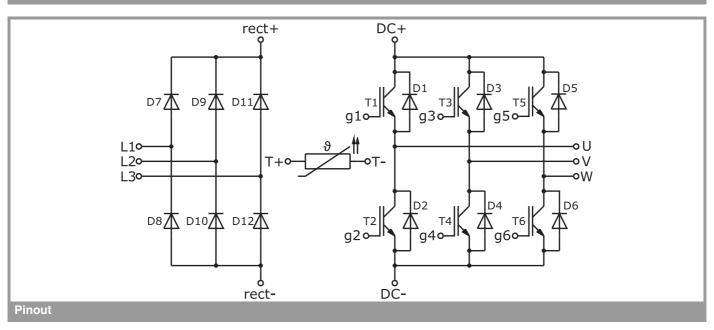


	Pin out							
Pin	Χ	Υ	Function	Pin	X	Υ	Function	
1	11,93	-11,50	g5	10	-3,28	-11,50	g1	
2	11,93	-6,90	W	11	-3,28	-5,80	U	
3	11,93	4,71	g6	12	-3,28	5,50	rect-	
4	11,93	8,3	T+	13	-3,28	11,50	g2	
5	11,93	11,50	T-	14	-11,08	-11,50	DC+	
6	4,33	-11,50	g3	15	-11,08	-8,30	rect+	
7	4,33	-5,80	V	16	-11,08	-1,68	L3	
8	4,33	6,95	g4	17	-11,08	4,93	L2	
9	4,33	10,15	DC-	18	-11,08	11,50	L1	

all values in mm



Pinout and Dimensions



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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